IPC ASSOCIATION ELECTRONIC	Material Com © Copyright 2005. international and Pa	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reser international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility								
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute								Materials and	rials and Mfg Information				
upplier	r Information													
Company name*				ompany unique ID			Unique ID Authority				Response Date*			
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	Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version	Manufacturing S	anufacturing Site		UOM	Unit Type	
		MURF8	60G	8A 600V UFR TO	)-220FP		2024-05-21		KR8		2009.84	mg	Each	
lanufa	cturing Process Information		Terminal Base	Alloy	-STD-020 MS	I. Poting	Pank Proce	ss Rody Tampa	atura May Tima s	t Daak Tampa	ratura Numb	or of Poflow Cv	clas	
8		CU Allov NA			L Katilig	Peak Process Body Temperature Max Time  0 C 30		1.	seconds   Number of Reflow Cycles   Seconds   3					
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RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its keloardine shall encompass all such components. Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier shall applier of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		'Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-6_								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.55	mg	Supplier	Silicon (Si)	7440-21-3		3.55	mg
Die Attach	82.98	mg	Supplier	Silver (Ag)	7440-22-4		1.2447	mg
			A	Lead (Pb)	7439-92-1	7a	77.5863	mg
			Supplier	Tin (Sn)	7440-31-5		4.149	mg
Lead Frame	1236.66	mg	Supplier	Copper (Cu)	7440-50-8		1236.66	mg
Mold Compound-Black	679.88	mg		Epoxy resin	proprietary data		47.5916	mg
			Supplier	Phenolic Resin	Proprietary Data		47.5916	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		101.982	mg
			Supplier	Carbon Black (C)	1333-86-4		3.3994	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		479.3154	mg
Plating	6.36	mg	Supplier	Tin (Sn)	7440-31-5		6.36	mg
Wire Bond - Al	0.41	mg	Supplier	Aluminum (Al)	7429-90-5		0.41	mg